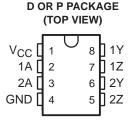
SLLS112C - OCTOBER 1980 - REVISED APRIL 1994

- Meets or Exceeds ANSI Standard EIA/TIA-422-B
- Operates From a Single 5-V Power Supply
- Drives Loads as Low as 50 Ω up to 15 Mbps
- TTL- and CMOS-Input Compatibility
- Output Short-Circuit Protection
- Interchangeable With National Semiconductor™ DS9638



description

The uA9638C is a dual high-speed differential line driver designed to meet ANSI Standard EIA/TIA-422-B. The inputs are TTL and CMOS compatible and have input clamp diodes. Schottky-diode-clamped transistors are used to minimize propagation delay time. This device operates from a single 5-V power supply and is supplied in an 8-pin package.

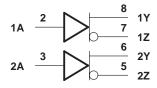
The uA9638 provides the current needed to drive low-impedance loads at high speeds. Typically used with twisted-pair cabling and differential receiver(s), base-band data transmission can be accomplished up to and exceeding 15 Mbps in properly designed systems. The uA9637A dual line receiver is commonly used as the receiver. For even faster switching speeds in the same pin configuration, see the SN75ALS191.

The uA9638C is characterized for operation from 0°C to 70°C.

logic symbol†

1A 2 7 17 12 6 2Y 2Z

logic diagram





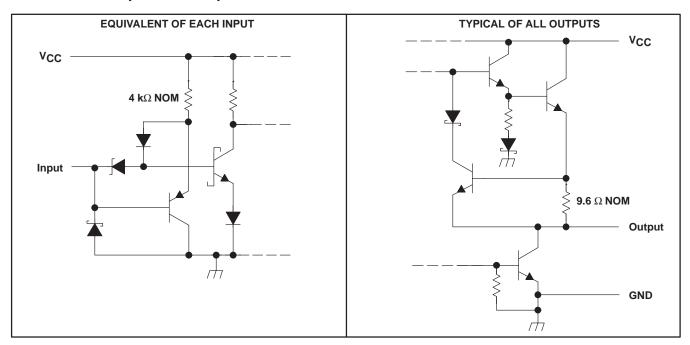
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[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 7 V
Input voltage range, V _I	0.5 V to 7 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	
Lead temperature 1,6 mm (1/16 inch) from 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage values except differential output voltages are with respect to network GND.

DISSIPATION RATING TABLE

PACKAGE	T _A = 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING			
D	725 mW	5.8 mW/°C	464 mW			
Р	1000 mW	8.0 mW/°C	640 mW			

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, V _{IH}	2			V
Low-level input voltage, V _{IL}			0.8	V
High-level output current, IOH			-50	mA
Low-level output current, IOL			50	mA
Operating free-air temperature, T _A	0		70	°C



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electrical characteristics over operating free-air temperature range (unless otherwise noted)

PARAMETER		Т	MIN	TYP [†]	MAX	UNIT		
VIK	Input clamp voltage	$V_{CC} = 4.75 \text{ V}, I_{I} = -18 \text{ mA}$			-1	-1.2	V	
Vou	High-level output voltage	$V_{CC} = 4.75 \text{ V},$	V _{IH} = 2 V,	$I_{OH} = -10 \text{ mA}$	2.5	3.5		V
Vон	r light-level output voltage	V _{IL} = 0.8 V		$I_{OH} = -40 \text{ mA}$	2			V
VOL	Low-level output voltage	$V_{CC} = 4.75 \text{ V},$ $I_{OL} = 40 \text{ mA}$	V _{IH} = 2 V,	V _{IL} = 0.8 V,			0.5	٧
IVOD1	Magnitude of differential output voltage	$V_{CC} = 5.25 \text{ V},$	I _O = 0			2	2V _{OD2}	V
IV _{OD2} I	Magnitude of differential output voltage				2			V
ΔIV _{OD} I	Change in magnitude of differential output voltage‡	$V_{CC} = 4.75 \text{ V to } 5.25 \text{ V}, \qquad R_{L} = 100 \Omega,$				±0.4	٧	
Voc	Common-mode output voltage§	See Figure 1					3	V
ΔIVOCI	Change in magnitude of common-mode output voltage‡						±0.4	V
			V _O = 6 V			0.1	100	
IO	Output current with power off	VCC = 0	$V_0 = -0.25 \text{ V}$			-0.1	-100	μΑ
			$V_0 = -0.25 \text{ V to 6 V}$				±100	
Ц	Input current	$V_{CC} = 5.25 \text{ V},$	V _I = 5.5 V				50	μΑ
ΙΗ	High-level input current	$V_{CC} = 5.25 \text{ V},$	V _I = 2.7 V				25	μΑ
Ι _Ι L	Low-level input current	$V_{CC} = 5.25 \text{ V},$	V _I = 0.5 V				-200	μΑ
los	Short-circuit output current¶	V _{CC} = 5.25 V,	V _O = 0		-50		-150	mA
Icc	Supply current (both drivers)	V _{CC} = 5.25 V,	No load,	All inputs at 0 V		45	65	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER		TEST CONDITIO	MIN	TYP	MAX	UNIT	
t _d (OD)	Differential output delay time	C 15 pE	Rι = 100 Ω.	See Figure 2		10	20	ns
t _t (OD)	Differential output transition time	$C_L = 15 pF$,	$RL = 100 \Omega$	See Figure 2		10	20	ns
t _{sk(o)}	Output skew		See Figure 2			1		ns

^{‡∆|}V_{OD}| and ∆|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level or vice versa.

[§] In Standard EIA-422-A, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage, VOS.

[¶] Only one output at a time should be shorted, and duration of the short circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION

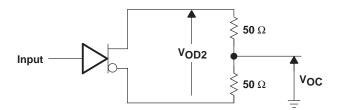
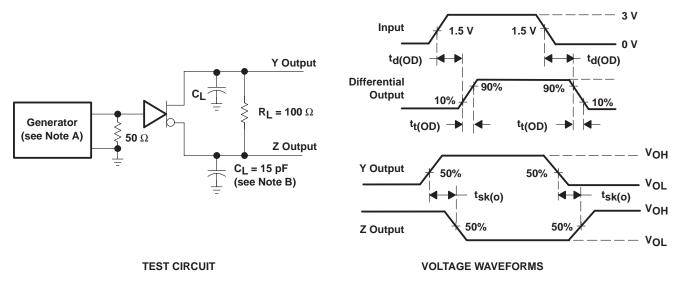


Figure 1. Differential and Common-Mode Output Voltages



NOTES: A. The input pulse generator has the following characteristics: $Z_O = 50 \ \Omega$, PRR $\leq 500 \ kHz$, $t_W = 100 \ ns$, $t_T = \leq 5 \ ns$.

B. C_L includes probe and jig capacitance.

Figure 2. Test Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UA9638CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9638CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
UA9638CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA9638CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA9638CDR	SOIC	D	8	2500	340.5	338.1	20.6

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm